ABSOCIATION CONNECTING ELECTRONICS INDUSTRIES® INTERNATION CONNECTING	burn. Illinois. A	ll rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of the s encompasse	substances es all lowe	within the er level mat	manufacture erials for wh	er listed iter hich the mar	n. Note: nufacture	if the item is an as r has engineering	sembly with lower responsibility.	
2-21.1 IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials					uls and Mfg	s and Mfg Information			
Supplier Information														
Company name* Company unique ID				Unique ID Authority						Response Date*				
nsemi										2024-04-27				
Contact Name	Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards	duct-Env-Stewards Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Representative				Phone - Representative*					Email - Representative*					
Product-Env-Stewards Product Enviro Compliance				NA						Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iter	n Number	Mfr Item Name			Effective Dat	e Version	L	Manufacturing Site		W	eight*	UOM	Unit Type	
NSS20:	S20501UW3T2G 20V NPN LOW VC		VCE(SAT) XTR	1	2024-04-27	27 MY1			9.6	53	mg	Each		
Manufacturing Proccess Information		·			·							·	·	
Terminal Plating / Grid Array Material	Terminal Base Alloy J-STD-020			Rating	Peak Pro	Peak Process Body Temperature Max Time at Pea			me at Peak	k Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU Alloy 1		1		260		C	30		seconds	3				
Comments														
evel 1 - maximum time at peak temperature during s	dering is 10-3	0 seconds												
For more information regarding material composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select select a RoHS exemption, if appli sigma range of distribution unless	cable [E] enter the weigh	Requester or Supplier) [B t of the substance or the Pl	] select the substa PM concentration	ance category (JIG or Requester) or enter [F] Optionally enter the positive (+) ar	er a value (Supplier). [C] selec d negative (-) tolerance in per	t the substance (JI cent (Note: percer	G) or enter the substa t tolerance values are	nce and CAS (Other). [D] expected to cover a 3
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.36	mg	Supplier	Silicon (Si)	7440-21-3		0.36	mg
Die Attach	0.14	mg	Supplier	Silver (Ag)	7440-22-4		0.119	mg
			Supplier	Epoxy resins	129915-35-1		0.021	mg
Lead Frame 2.69	2.69	mg	Supplier	Silver (Ag)	7440-22-4		0.0538	mg
			Supplier	Iron (Fe)	7439-89-6		0.0592	mg
			Supplier	Copper (Cu)	7440-50-8		2.577	mg
Mold Compound-Black 5	5.8	mg		Epoxy Phenol Resin	proprietary data		0.522	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		5.278	mg
Plating	0.57	mg	Supplier	Tin (Sn)	7440-31-5		0.57	mg
Wire Bond - Cu	0.07	mg	Supplier	Copper (Cu)	7440-50-8		0.07	mg